IPC ASSOCIATION CONNEC	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information			
upplier Info	rmation														
Company name* Company u			Company uni	que ID Uniq			Unique ID Authority			Resp	Response Date*				
nsemi										2023-	2023-06-08				
Contact Name		Title - Contact			I	Phone - Contact*				Emai	Email - Contact*				
Product-Env-Ste	ewards		Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			I	Phone - Representative*			Emai	Email - Representative*					
Product-Env-Stewards Pr			Product Envi	oduct Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Reque	Requester Item Number Mfr Iter		Number	Number Mfr Item Name			Effective Date	Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		ASX342 D0-DP	ATSC00XPE	VGA 1/4 CIS SOO	2		2023-06-08			TA1		108.92	mg	Each	
Ianufacturin	ng Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy	-STD-020 MS	L Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						cles				
SnAgCu		CU Alloy	3			260		C	30	sec	conds 3				
omments															
<b>ITENTION:</b> M	ISL 3 Rated item requires	Bake and D	ry Pack (after	electrical test)											
or more inform	ation regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the complance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	29.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5421	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5421	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5421	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1544	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5421	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5421	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4353	mg
Lid Attach	1.52	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.684	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.304	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.19	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0076	mg
			Supplier	Curative	Proprietary Data		0.0304	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.304	mg
Mold Compound-Black	8.1	mg		Phenolic Resin	proprietary data		1.215	mg
			Supplier	Oxirane	39817-09-9		1.215	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		0.243	mg
			Supplier	Carbon Black (C)	1333-86-4		0.081	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.184	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.162	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg
			Supplier	Tin (Sn)	7440-31-5		23.6907	mg
			Supplier	Copper (Cu)	7440-50-8		0.1227	mg
Substrate and Solder Mask	19.1	mg	Supplier	Bis(3-ethyl-5-methyl-4-maleimidophenyl)methane	105391-33-1		0.2139	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	2.4754	mg
			Supplier	Zinc (Zn)	7440-66-6	0.0287	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.445	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.2139	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.1108	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0019	mg
			Supplier	Acetophenone Derivative	Proprietary Data	0.6666	mg
			Supplier	Carbon Black (C)	1333-86-4	0.1108	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.1108	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	2.292	mg
			В	Nickel (Ni)	7440-02-0	0.2693	mg
			Supplier	Gold (Au)	7440-57-5	0.0096	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	1.3351	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.2139	mg
			Supplier	Copper (Cu)	7440-50-8	7.1549	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	3.4475	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg